



(19)

(11) Publication number: **06073598 A**

Generated Document

PATENT ABSTRACTS OF JAPAN

(21) Application number: 03133502

(51) Intl. Cl.: C25D 17/00 C25D 5/08 H01L 21/288

(22) Application date: 08.05.91

(30) Priority:

(43) Date of application
publication: 15.03.94(84) Designated contracting
states:

(71) Applicant: SUGANUMA KEIICHIRO

(72) Inventor: SUGANUMA KEIICHIRO

(74) Representative:

**(54) METHOD FOR
PRODUCING
SEMICONDUCTOR AND
DEVICE THEREFOR**

(57) Abstract:

PURPOSE: To subject a semiconductor wafer to plating in a uniform thickness and to carry out chemical treatment or other treatment.

CONSTITUTION: A semiconductor wafer W is held over a treating vessel 1 with the top open so that the surface of the wafer W to be treated is positioned downward, a treating soln. is fed from plural parts in the treating vessel 1 and electric current is supplied between a lower electrode 2 and an upper electrode 3 disposed in the vessel 1 while allowing the treating soln. to overflow the vessel 1 to subject the semiconductor wafer W to plating, chemical treatment or other treatment.

COPYRIGHT: (C)1994,JPO&Japio

